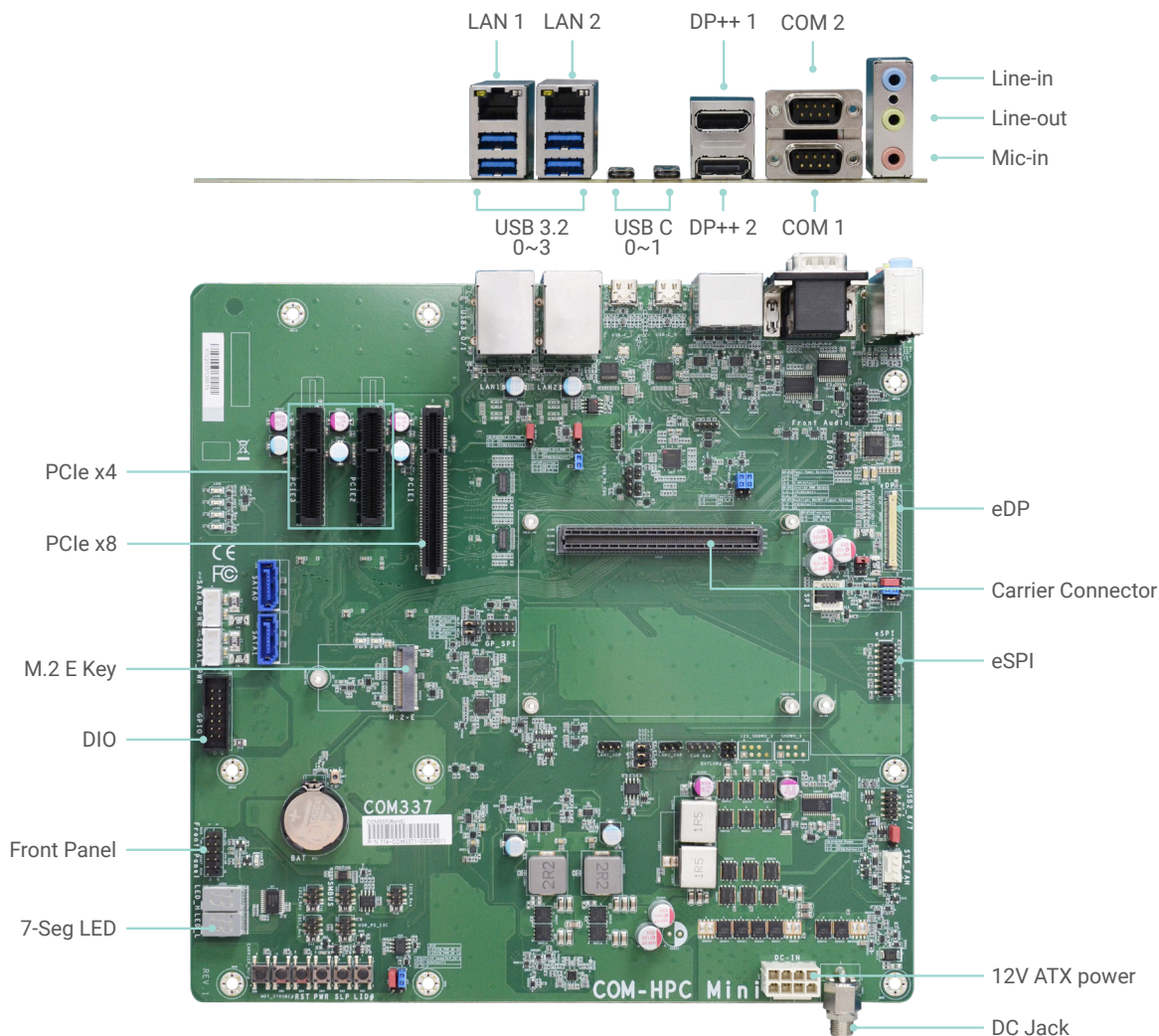


COM337

COM HPC Mini Carrier Board
microATX form factor

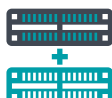


KEY FEATURES



Multiple Displays

2 DP++, eDP



Multiple Expansion

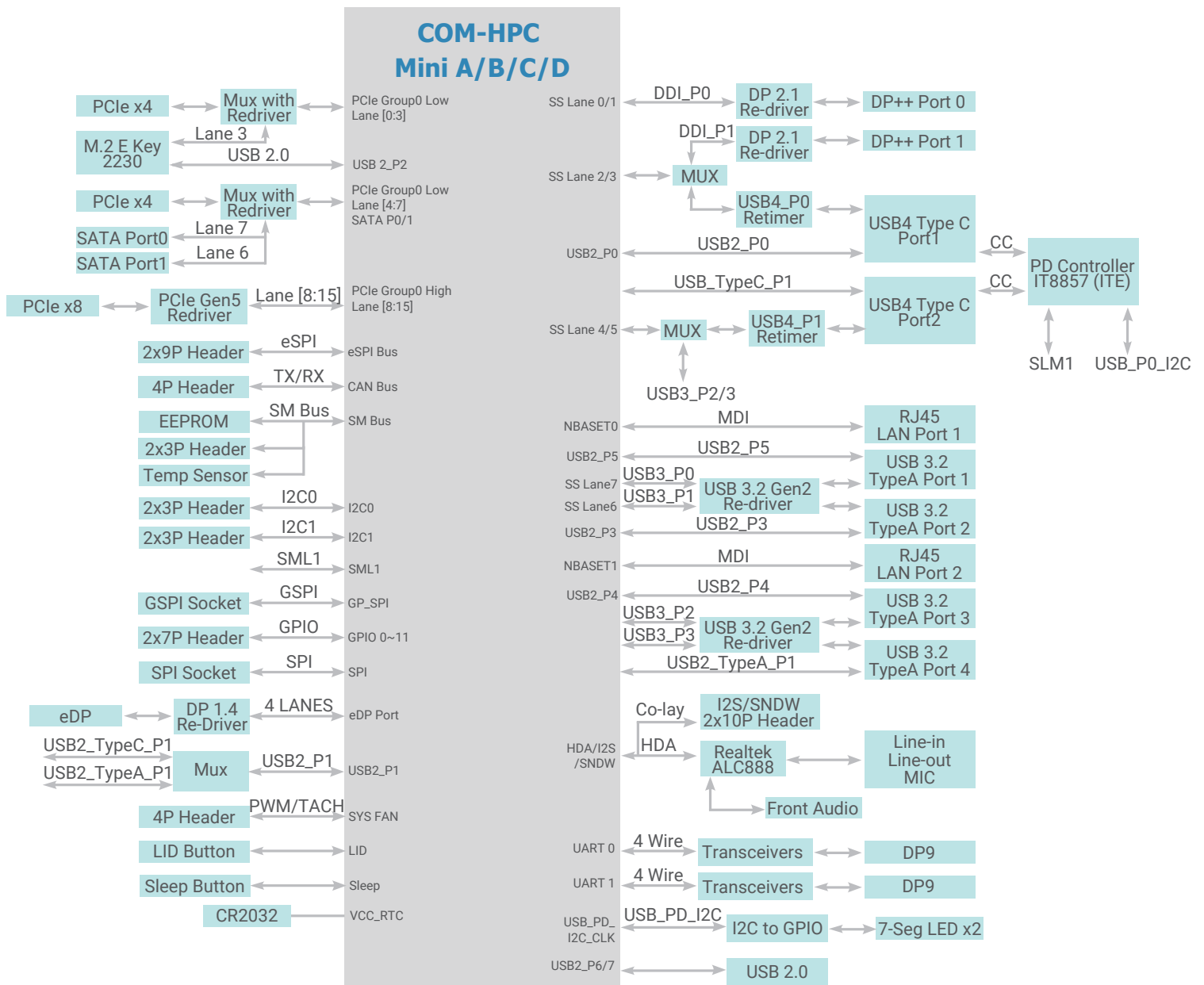
1 PCIe x8, 2 PCIe x4,
1 M.2 E Key 2230



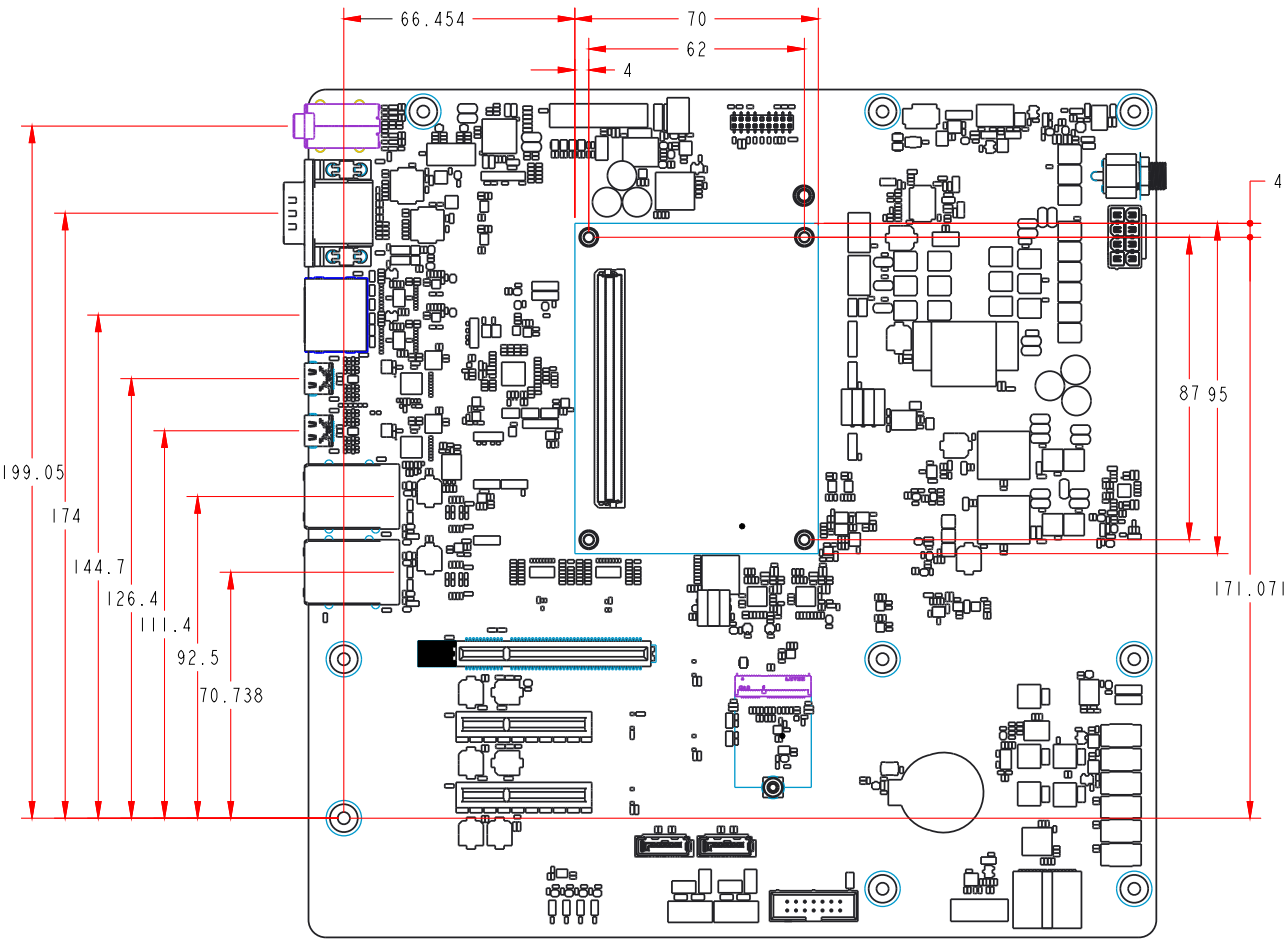
Rich I/O

2 2.5 GbE, 4 USB 3.2,
2 USB4 (Type-C)

BLOCK DIAGRAM



MECHANICAL DRAWING



SPECIFICATION

GRAPHICS	Display	2 x DP++ 1 x eDP
EXPANSION	Interface	1 x PCIe x8 2 x PCIe x4 1 x M.2 E Key 2230
AUDIO	Audio Codec	Realtek ALC888S-VD2-GR
I/O	Ethernet	2 x 2.5 GbE (RJ-45)
	USB	2 x USB4 Type-C (co-layout w/USB3.2, available upon request) 4 x USB 3. 2 (Gen 2)
	Display	2 x DP
	Serial	2 x DB9 (4-wires UART 0/1)
	Audio	1 x Line-in 1 x Line-out 1 x Mic-in
INTERNAL I/O	Display	1x eDP LCD Panel Connector
	Audio	1 x Audio (Line-out/Mic-in) 1 x S/PDIF
	SATA	2 x SATA 3.0 (up to 6Gb/s) 2 x SATA Power
	DIO	1 x 12-bit DIO
	eSPI	1 x eSPI
	I2C	2 x I2C
	SMBus	1 x SMBus
	GP_SPI	1 x GP_SPI
	SPI	1 x SPI
	CAN	1 x CAN bus
	FAN	1 x SYS_FAN (SmartFan support)
POWER	Type	1x 8-pin ATX power connector (12V DC_In) 8.5V-20V DC in jack
	Connector	1 x 8-pin ATX power connector 1 x DC-in jack
	RTC Battery	CR2032 Coin Cell
ENVIRONMENT	Temperature	Operating: -40 to 85°C Storage: -40 to 85°C
	Humidity	Operating: 5 to 90% RH Storage: 5 to 90% RH
	MTBF	TBD
MECHANICAL	Dimensions	microATX Form Factor 244mm (9.6") x 244mm (9.6")
	Compliance	PICMG® COM-HPC® R1.3
CERTIFICATIONS	Certifications	CE, FCC, RoHS

ORDERING INFORMATION

Model Name	Part Number	2.5GbE	USB 3.2	DP++	Power	Thermal	Temp.
COM337	770-CM3371-000G	2	4	2	ATX/AT	NA	-40 to 85°C

PACKING LIST

• 1 COM337 board
